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United States Design Patent

Otsuka

(10)

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(54) EARPPHONE

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USPC D14/223

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381/380–381, 322, 328
CPC H04R 1/10; H04R 25/00; H04R 25/02;
H04R 1/1066; H04R 1/1016; H04R
5/033; H04R 5/0335; H04R 1/1058;
H04R 1/1008; H04R 1/1091
See application file for complete search history.

(56) References Cited

U.S. PATENT DOCUMENTS

2,477,046 A * 7/1949 Davenport H04R 25/65
381/328

2,513,985 A * 7/1950 Woodruff H04R 1/1008
381/372

2,584,402 A * 2/1952 Volkmann H04R 1/1083
D14/242

2,971,065 A * 2/1961 Busse H04R 25/652
381/189

4,539,708 A * 9/1985 Norris H04B 1/088
455/100

D287,765 S * 1/1987 Topholm D24/174

D481,709 S * 11/2003 Solderits D14/223

7,717,226 B2 * 5/2010 Purcell A61F 11/14
381/372

7,757,807 B1 * 7/2010 Martinez A61B 7/02
181/131

D637,997 S * 5/2011 Peller D14/205

D647,514 S * 10/2011 Wikel D14/223

D719,139 S * 12/2014 Henry D14/223

D725,082 S * 3/2015 Palmborg D14/223

D733,102 S * 6/2015 Palmborg D14/223

D818,989 S * 5/2018 Silva D14/205

D822,646 S * 7/2018 Dang D14/223

D845,932 S * 4/2019 Lu D14/223

D847,778 S * 5/2019 Hardi D14/205

(Continued)

FOREIGN PATENT DOCUMENTS

CN 307475552 * 7/2022

EM 006792263-0001 * 8/2019

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(57) CLAIM

The ornamental design for an earphone, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of an earphone showing my new design;

FIG. 2 is a front view thereof;

FIG. 3 is a rear view thereof;

FIG. 4 is a left side view thereof;

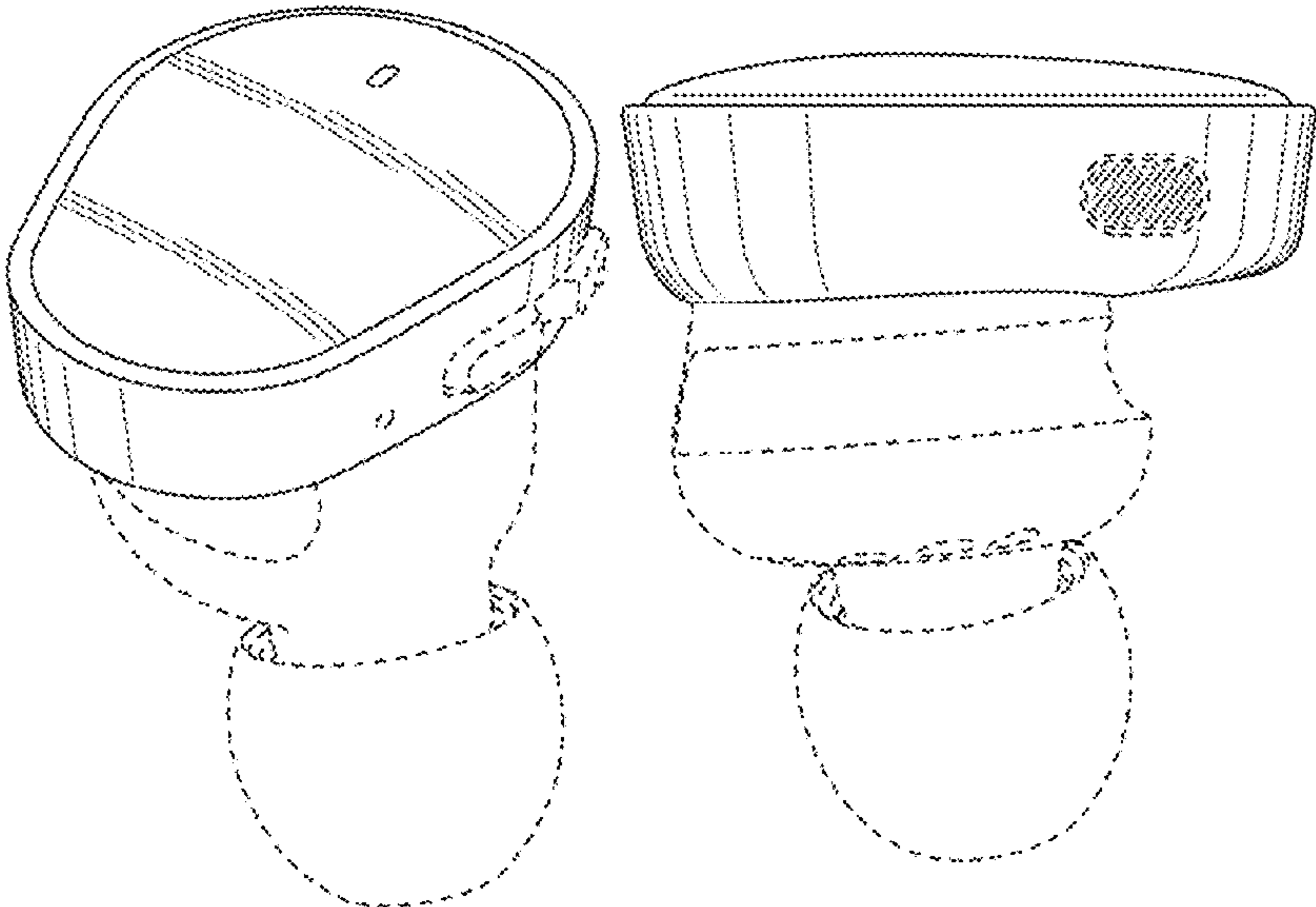
FIG. 5 is a right side view thereof;

FIG. 6 is a top view thereof; and,

FIG. 7 is a bottom view thereof.

The broken lines shown in the figures depict portions of the earphone that form no part of the claimed design.

1 Claim, 4 Drawing Sheets



(56) **References Cited**

U.S. PATENT DOCUMENTS

D860,975	S	*	9/2019	Briggs		D14/223
D889,441	S	*	7/2020	Lin		D14/223
D892,087	S	*	8/2020	Briggs		D14/223
D897,319	S	*	9/2020	Wang		D14/223
D905,664	S	*	12/2020	He		D14/223
D920,288	S	*	5/2021	Vautour		D14/223
D925,497	S	*	7/2021	Laffon de Mazieres		D14/223
D926,162	S	*	7/2021	Dang		D14/223
D926,163	S	*	7/2021	Williamson		D14/223
D930,617	S	*	9/2021	Tanaka		D14/223
D934,841	S	*	11/2021	Takubo		D14/223
D947,817	S	*	4/2022	Nakamura		D14/223
D954,027	S	*	6/2022	Chen		D14/223
D954,683	S	*	6/2022	Huang		D14/223
D964,322	S	*	9/2022	Miyata		D14/223
11,632,618	B1	*	4/2023	Chien		H04R 3/04 381/74
D986,858	S	*	5/2023	Reimann		D14/223
D989,043	S	*	6/2023	Levine		D14/223
D991,227	S	*	7/2023	Miyata		D14/223
D997,919	S	*	9/2023	Dryden		D14/223
D1,000,425	S	*	10/2023	Wei		D14/223
2002/0090104	A1	*	7/2002	Ma		H04R 1/1091 381/370
2019/0208112	A1	*	7/2019	Kleinbeck		G01R 29/0892
2020/0021905	A1	*	1/2020	Briggs		H04R 1/1066
2021/0006890	A1	*	1/2021	Zhang		H04R 1/04
2023/0111906	A1	*	4/2023	Takano		H04R 1/1016 381/74

* cited by examiner

FIG. 1

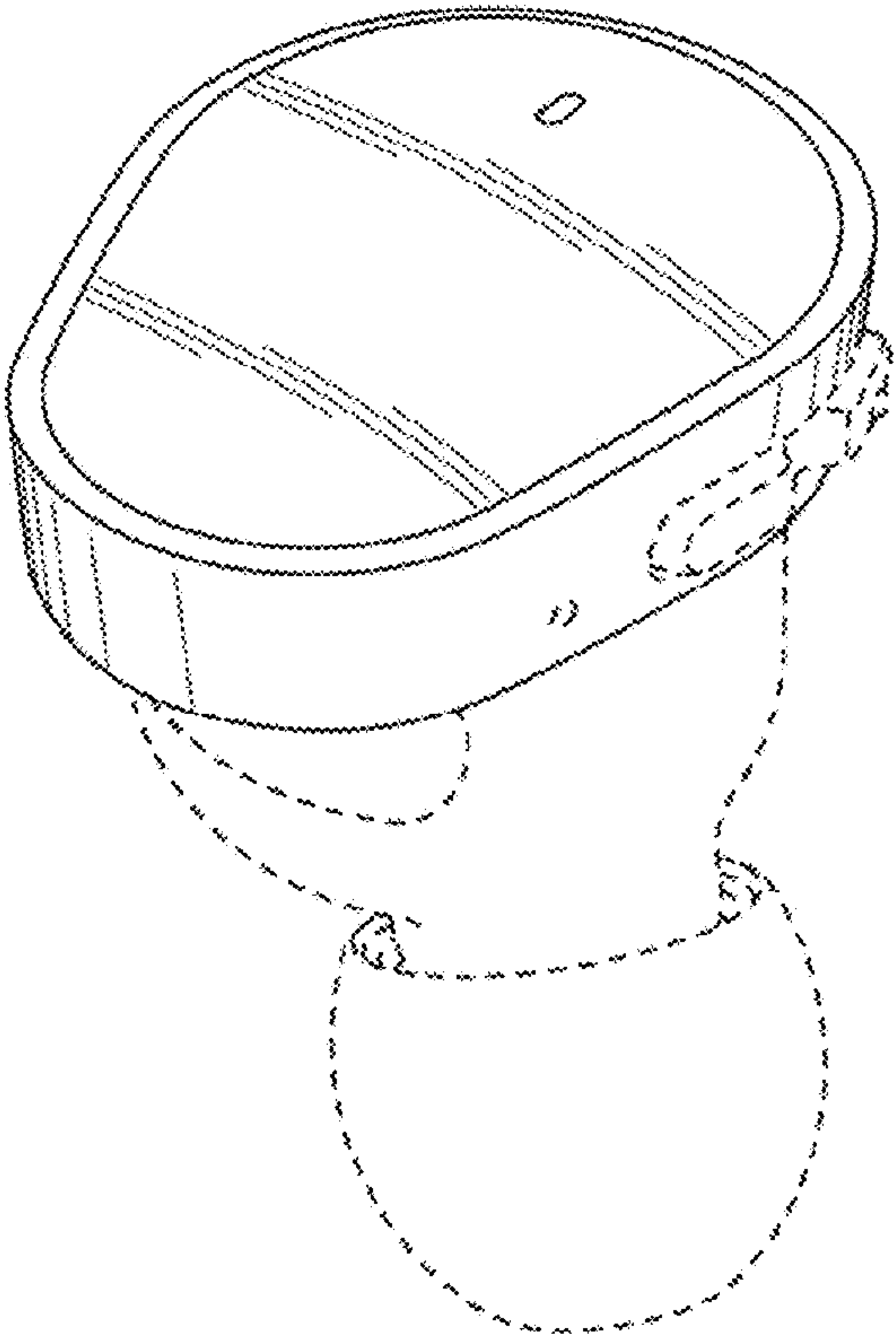


FIG. 2

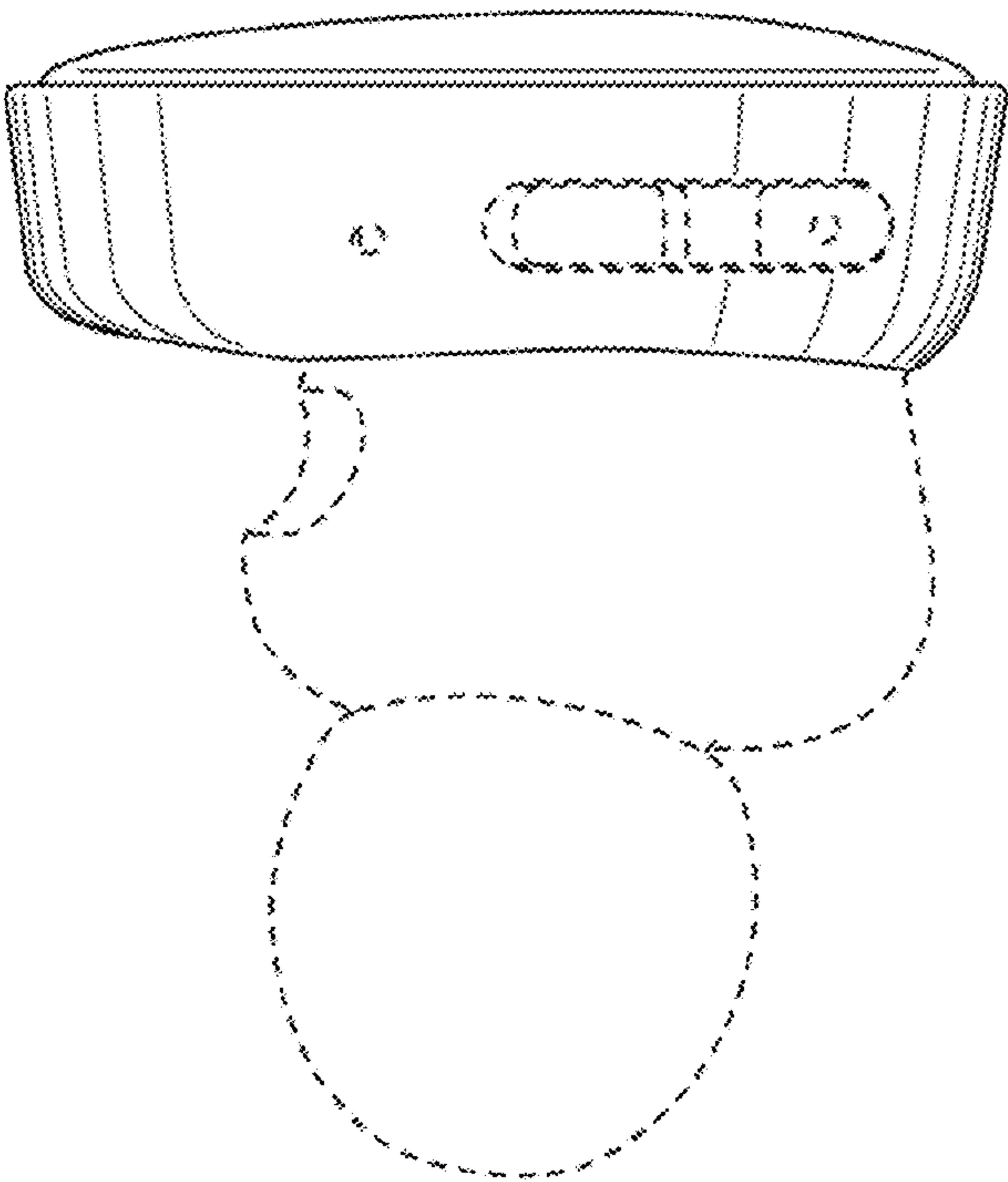


FIG. 3

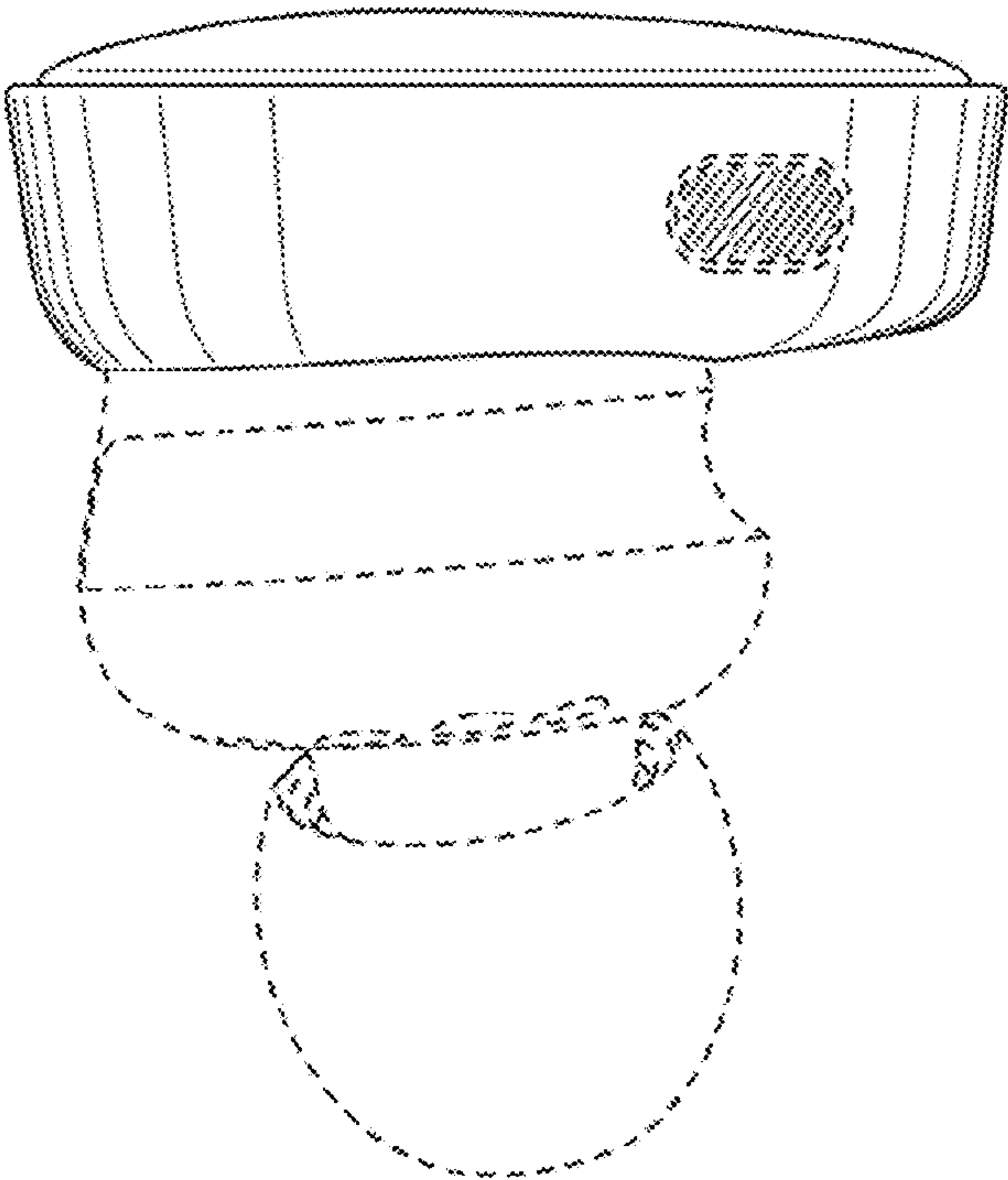


FIG. 4

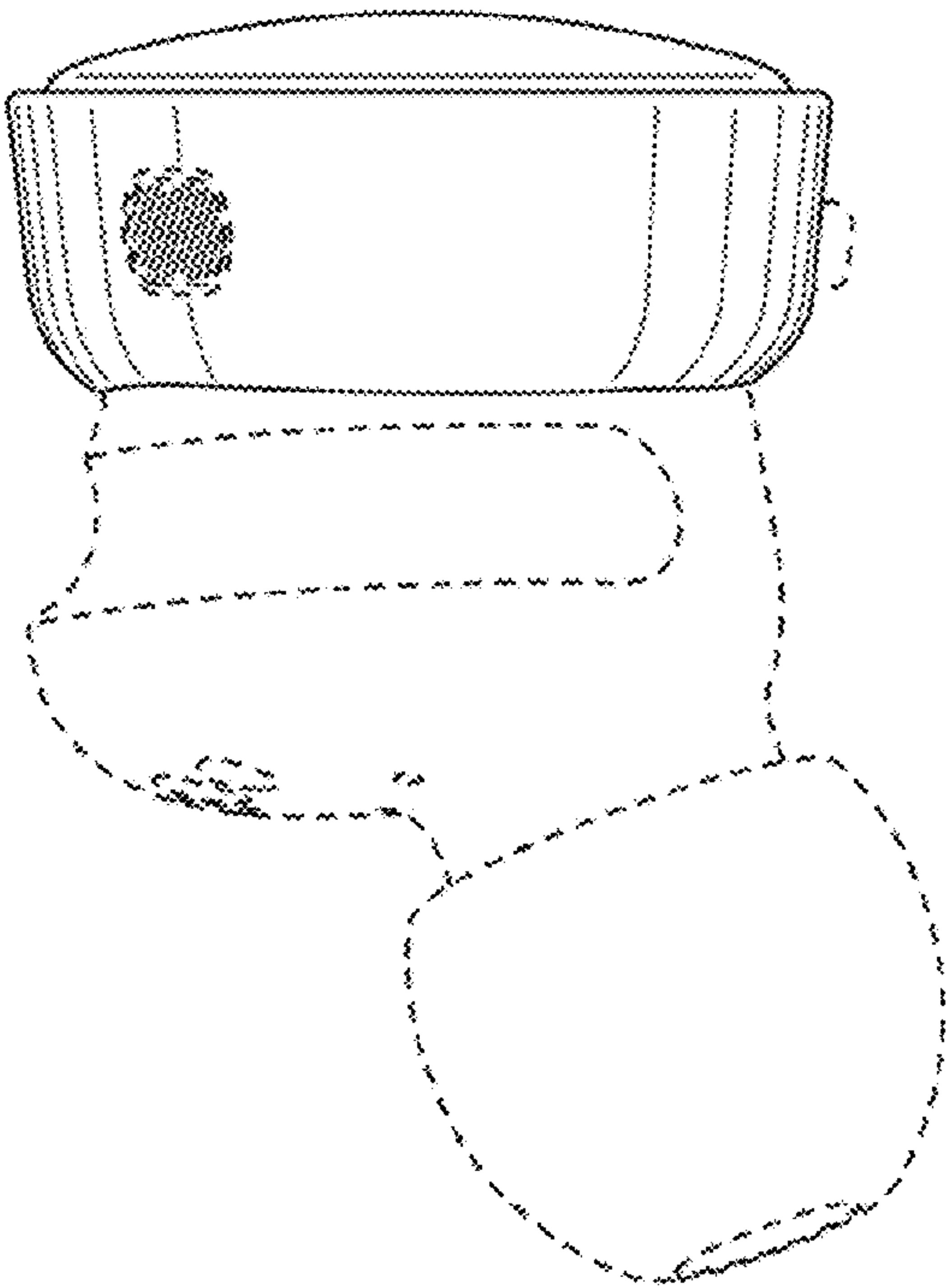


FIG. 5

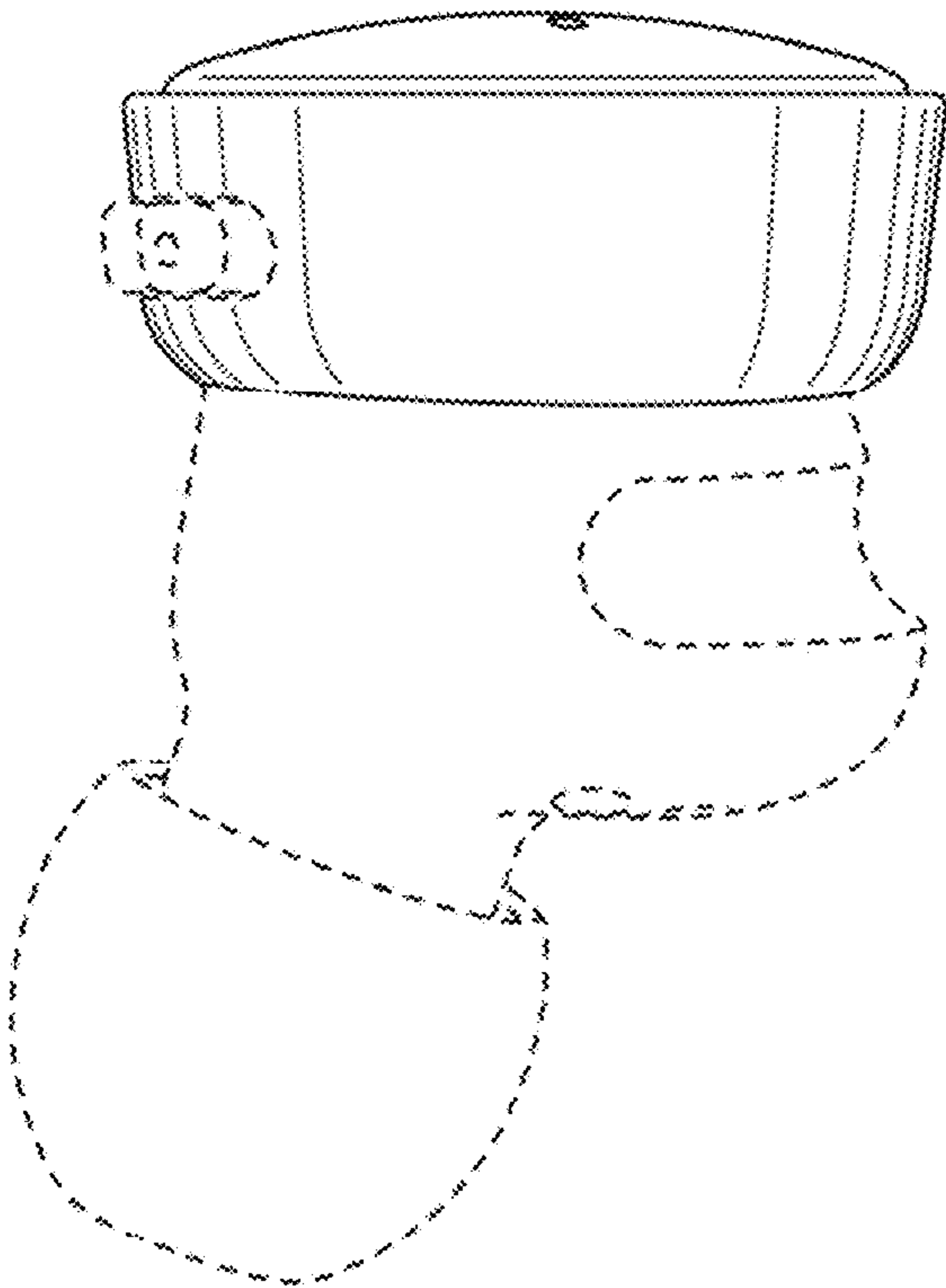


FIG. 6

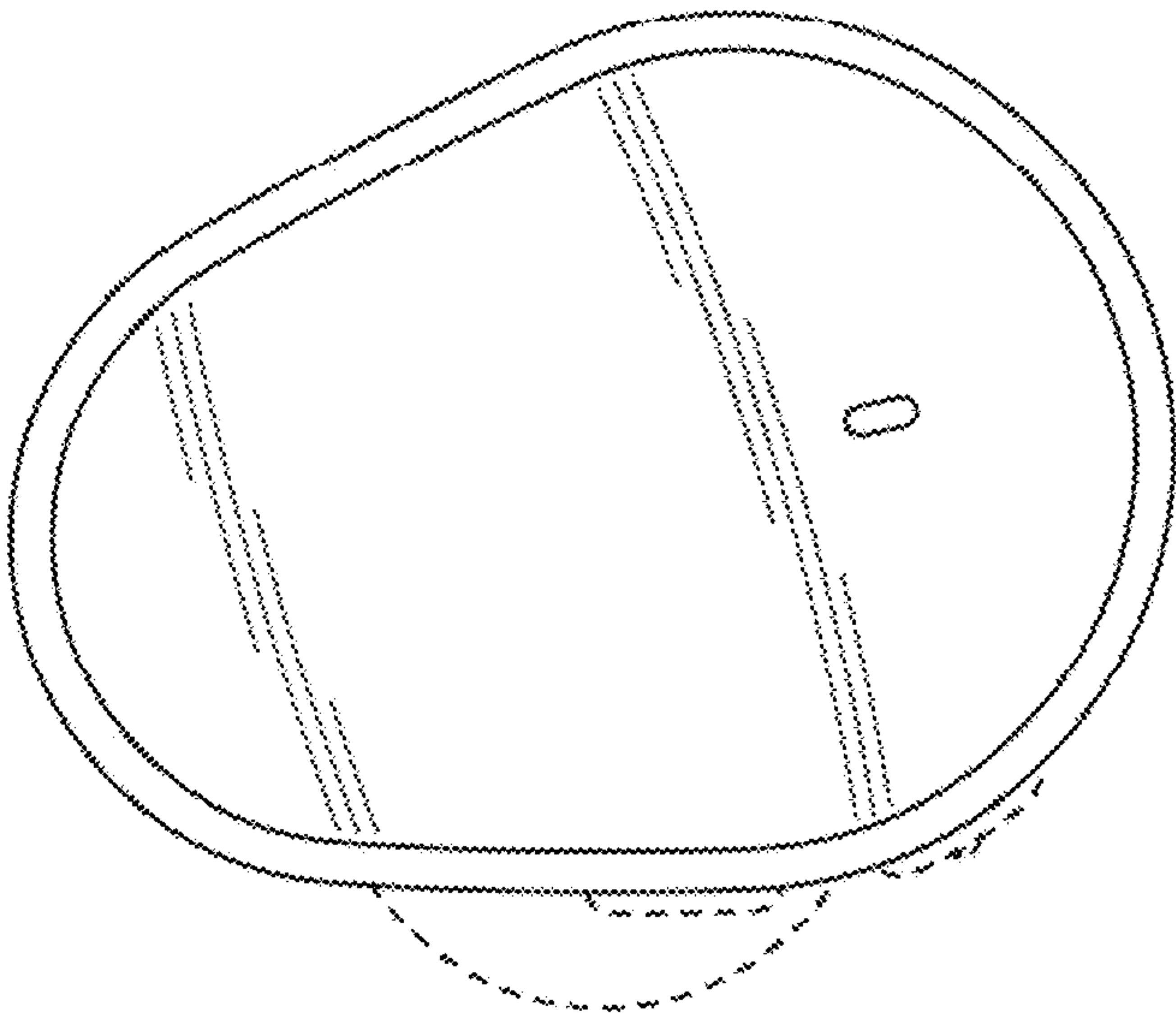


FIG. 7

